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IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Tsuyoshi HIRAMATSU et al.

Appl. No.: 09/936,930

ART UNIT: 1771

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Examiner: Victor S Chang

For: PRESSURE SENSITIVE ADHESIVE SHEETS FOR REMOVAL
OF SOLVENT-CONTAINING SUBSTANCES

DECLARATION UNDER 37 C.F.R. 1.132

Assistant Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

Sir:

I, Tsuyoshi HIRAMATSU, a citizen of Japan and residing at NITTO DENKO CORPORATION 1-2, Shimohozumi 1-chome, Ibaraki-shi, OSAKA, declare and say that:

I was graduated from Department of Chemistry, School of Science, Nagoya University.

From January, 1991 up till the present, I have been engaged in development of pressure-sensitive adhesive tape and relatives since I entered the company.

I am one of the inventors of the above-identified application and am familiar with the subject matter thereof.

I have read the Official Action mailed on March 18, 2005 and the references cited therein and am familiar with the subject matter thereof.

I declare that the solid adhesive layer is explicitly or inherently supported in the present specification.

EXPOSITION:

A pressure-sensitive adhesive sheet for removal of a solvent-containing substance comprises a sheet each including a foam layer formed on a substrate or a non-foamed pressure-sensitive adhesive layer on a substrate. For example, the former sheet is prepared by applying a mixture containing a resin and a foaming agent to the substrate, and heating and foaming the applied mixture (page 48, lines 7 to 23 of the specification). The obtained foam layer has innumerable bubbles, and the volume thereof is from about 1.2 to 100 times as much as a layer without foaming treatment (page 47, lines 5 to 7 of the specification). On the other hand, the latter sheet is prepared by applying a pressure-sensitive adhesive composition to the substrate, and drying without foaming treatment (e.g. Example 5 et al.), so the obtained layer does not expand to be in 'solid' condition. However, it does not mean to exclude layers including fine foam. Namely, such fine foam is often made during the step of applying and drying the pressure-sensitive adhesive solution or others, and we can find such fine foam in the obtained layer when observing the cross section of the layer with the electron microscope. Furthermore, it also does not mean to exclude layers exhibiting a certain degree of elasticity because pressure-sensitive adhesives forming the layers are generally 'viscoelastic bodies'.

I declare further that all statements made herein of

my own knowledge are true and that all statements made on information and belief are to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the above-identified application or any patent issuing thereon.

This 27th day of July, 2005

Tsuyoshi Hiramatsu

Tsuyoshi HIRAMATSU